

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



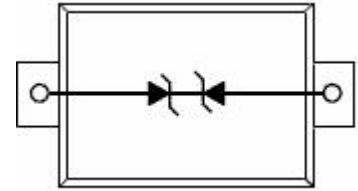
PLED

Product data sheet

[www.msksemi.com](http://www.msksemi.com)

### Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.



SOD-323

### Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 200 Watts @ 8 x 20  $\mu$ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection

### Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

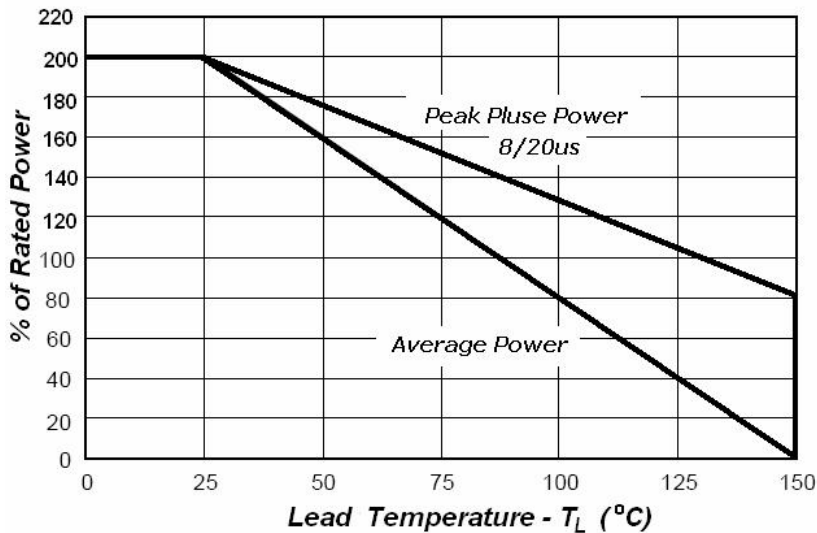
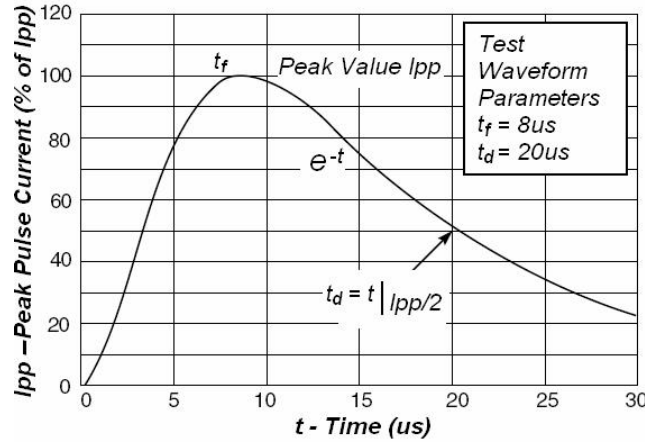
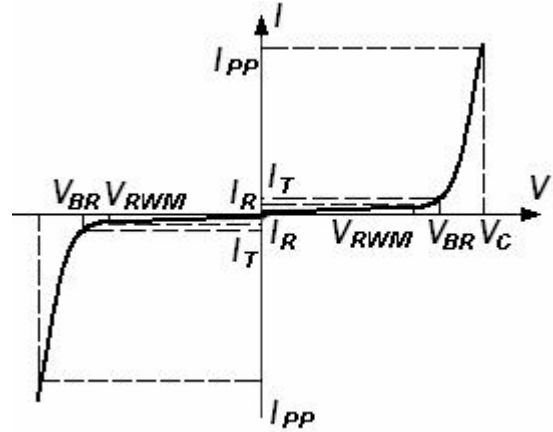
P/N	V <sub>RWM</sub> (V)	I <sub>R</sub> ( $\mu$ A) @ V <sub>RWM</sub>	V <sub>BR</sub> (V)@ I <sub>T</sub> (Note 1)	I <sub>T</sub>	V <sub>C</sub> (V) @ I <sub>PP</sub> =5 A*	V <sub>C</sub> (V) @ Max I <sub>PP</sub> *	I <sub>PP</sub> (A)*	P <sub>PK</sub> (W)*	C (pF)
	Max	Max	Min	mA	Typ	Max	Max	Max	Typ
MSESD3Z5.0C	5.0	1	5.6	1.0	11.6	18.6	9.4	174	25

### Absolute Ratings (T<sub>amb</sub>=25°C )

Symbol	Parameter	Value	Units	
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20 $\mu$ s)	200	W	
T <sub>L</sub>	Maximum lead temperature for soldering during 10s	260	°C	
T <sub>stg</sub>	Storage Temperature Range	-55 to +155	°C	
T <sub>op</sub>	Operating Temperature Range	-40 to +125	°C	
T <sub>j</sub>	Maximum junction temperature	150	°C	
	IEC61000-4-2 (ESD)	air discharge contact discharge	$\pm$ 15 $\pm$ 8	KV
	IEC61000-4-4 (EFT)		40	A
	ESD Voltage	Per Human Body Model	16	KV

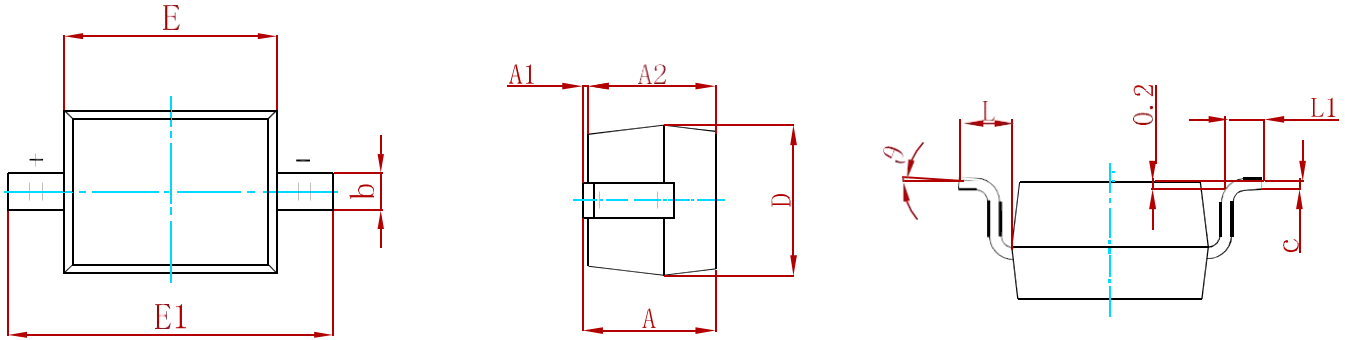
**Electrical Parameter**

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$I_T$	Test Current
$V_{BR}$	Breakdown Voltage @ $I_T$



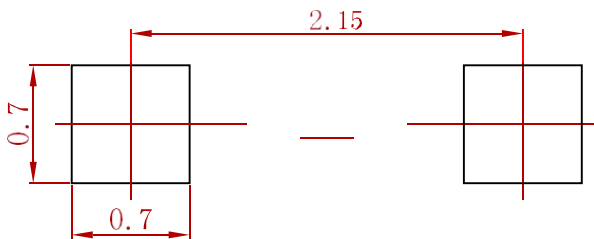
**Fig2.Power Derating**

**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

**Suggested Pad Layout**



- Note:**
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
MSESD3Z5.0C	SOD-323	3000

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